IP E1284.64722

PATENT APPLICATION 11/02

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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licant:	Li et al.	)	
Serial No.:	09/662,682	the United States F in an envelope add	at this paper is being deposited with Postal Service as FIRST-CLASS mail Pressed to: Assistant Commissioner
Filed:	September 15, 2000	6/13/02	ngton, D.C 30231, on this date.
For:	METAL-ASSISTED CHEMICAL	Date  F-CLASS.WCM  Appr. February 20, 1998	Registration No. <u>35/32</u> Attorney for Applicant
	ETCH POROUS SILICON FORMATION METHOD	)	ORIGIA OF
Art Unit:	1765	) )	OF OF OF PAPERS
Examiner:	Vinh, Lan	)	
AMENDMENT A			RECEIVED JUN 2,5 2002
Assistant Commissioner for Patents			2002

Dear Sir:

In response to the office action mailed March 13, 2002, please amend the application as follows:

## In the Specification:

Washington, D.C. 20231

Please replace the paragraph beginning on page 1, line 3 with the following re-written paragraph: